

Model Name: EBA31001-10-XXXX

BGA Heat Sink

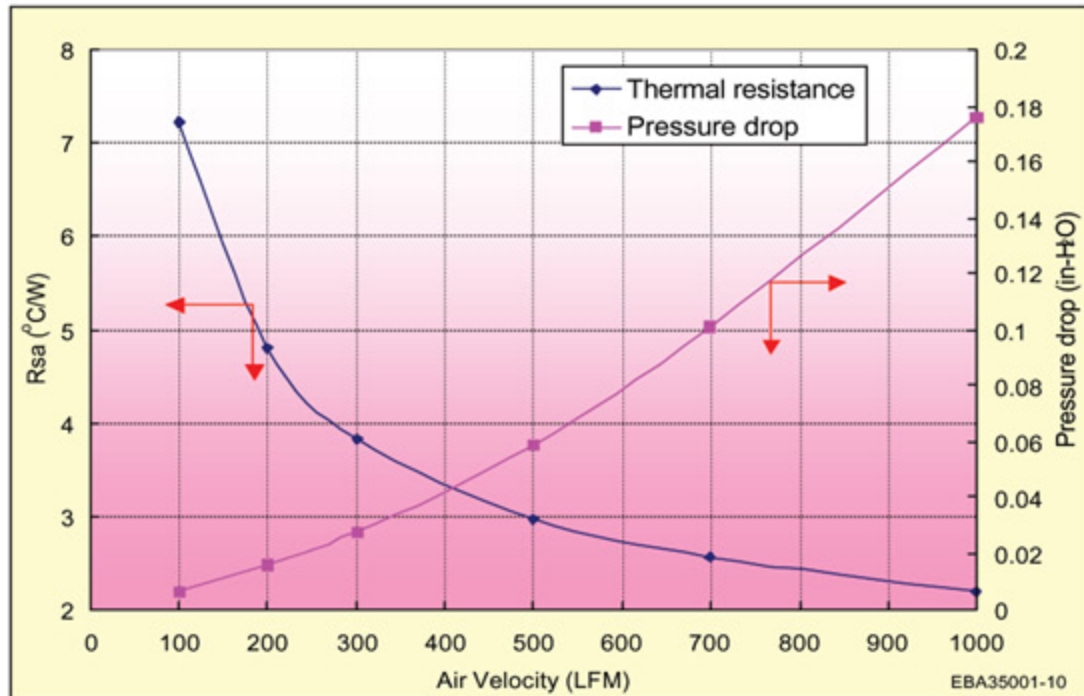
For 31x31 Chip set

*Specification:

1. Material: Aluminum 6063
2. Weight: 12 gm
3. Technology: Extrusion
4. Finish: Black Anodize
5. Heat Sink Dimension:
30.6 x 30.5 x 9.8 mm
6. Copper package and moulding
compound package available
7. Heat source size: Uniform
8. Thermal Pad option suffix
-T410=Chromerics T410 thermal interface pad
-T710=Chromerics T710 thermal interface pad
Blank=no thermal pad



*Performance Data:



AMERICAN THERMAL PRODUCTS

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